

Digital Interconnection Techniques and Characterization at GHz Frequencies

50 GHz Interconnect Design in Standard Silicon Technology, B. Kleveland, S. S. Wong, and T.L. Lee, Center for Integrated Systems, Stanford University, Stanford University, Stanford, CA

Accurate Characteristic Impedance Measurement on Silicon, D. F. Williams, U. Arz*, and H. Grabinski*, NIST, Boulder; *University of Hannover, Hannover, Germany

A Test Board for Multiport Immitance Measurement and Characterization of RF-IC Packages, A. Tripathi, R. Lutz, V. K. Tripathi, H. H. Wu*, J. W. Meyer, and B. Hutchison**, Dept. of Electrical and Computer Engineering, Oregon State Univesity, Corvallis, OR; *HP EEsof, Santa Rosa, CA; **Hewlett-Packard Co., Microwave Technology Division, Santa Rosa, CA

Analysis of Microvia Interconnects, R. Abhari and T. E. van Deventer, Department of Electrical and Computer Engineering, University of Toronto, Toronto, Ontario, Canada

Multi-Wire Microstrip Interconnections: A Systematic Analysis for the Extraction of an Equivalent Circuit, F. Alimanti, P Mezzanotte, L. Roselli, and R. Sorrentino, Instituto de Electronica, University of Perugia, Perugia, Italy